

AMENDMENTS TO CLAIMS

- Please amend pending claims 1, 6, 11, and 16 as indicated below. A complete listing of all claims and their status in the application are as follows:

- (Same changes applied to claims 6, 11, and 16)
1. (currently amended) A method for fabricating a semiconductor package, comprising:
- providing a substrate in a strip format;
  - attaching semiconductor devices in a strip format to the substrate;
  - applying an underfill between the semiconductor devices and the substrate;
  - applying a <sup>thin</sup> thermal interface material to the semiconductor devices;
  - attaching a flat panel heat spreader to <sup>the thermal interface material on</sup> each semiconductor device;
  - encapsulating all of the volume around-immediately surrounding the semiconductor devices except that volume filed by the substrate, the underfill between the semiconductor devices and the substrate, the thermal interface material applied to the semiconductor devices, the flat panel heat spreader attached to each semiconductor device, and other electronic devices assembled on the substrate, with open encapsulation, leaving the surface of the flat panel heat spreader opposite the substrate externally exposed; and
- Substantially all of the volume between the heat spreader and the substrate, except that occupied by the semiconductor devices and other electronic devices assembled on the substrate
- singulating individual semiconductor packages from the strip format.
2. (original) The method of claim 1 wherein the heat spreader is a pre-cut flat panel configuration.
3. (original) The method of claim 1 wherein the heat spreader is a continuous flat panel heat spreader attached over substantially the entire strip format.
4. (original) The method of claim 3 further comprising cutting the continuous flat panel heat spreader into individual heat spreader panels following attaching the flat panel heat spreader.
5. (original) The method of claim 3 further comprising dispensing an encapsulant for encapsulating the semiconductor devices and for attaching the flat panel heat spreader prior to attaching the flat panel heat spreader.